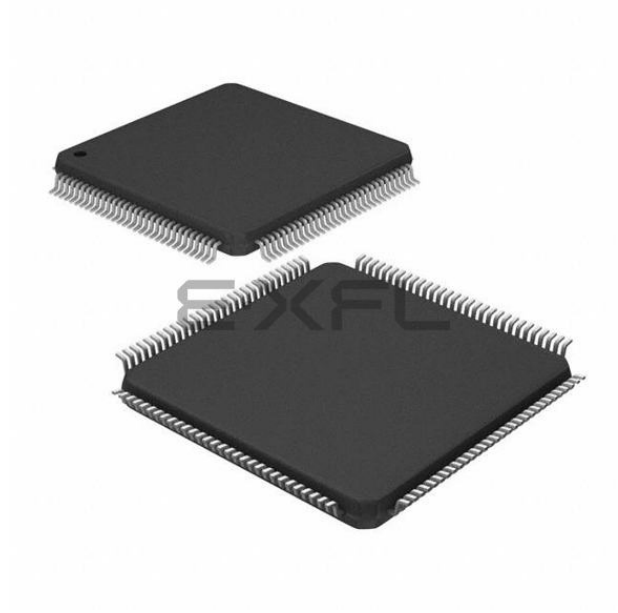
Infineon Technologies - MB90922NCSPMC-GS-247E1 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, LINbus, UART/USART
Peripherals	LCD, LVD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90922ncspmc-gs-247e1

FUJITSU SEMICONDUCTOR
DATA SHEET

DS07-13750-4E

16-bit Microcontroller

CMOS

F²MC-16LX MB90920 Series

MB90F922NC/F922NCS/922NCS/F923NC/F923NCS/ MB90F924NC/F924NCS/V920-101/V920-102

■ DESCRIPTION

The MB90920 series is a family of general-purpose FUJITSU SEMICONDUCTOR 16-bit microcontrollers designed for applications such as vehicle instrument panel control.

The instruction set retains the AT architecture from the F²MC-8L and F²MC-16LX families, with further refinements including high-level language instructions, extended addressing modes, improved multiplication and division operations (signed), and bit processing. In addition, long word processing is made possible by the inclusion of a built-in 32-bit accumulator.

Note : F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- Clock
  Built-in PLL clock frequency multiplication circuit.
  Selection of machine clocks (PLL clocks) is allowed among frequency division by two on oscillation clock, and multiplication of 1 to 8 times of oscillation clock (for 4 MHz oscillation clock, 4 MHz to 32 MHz).
  Operation by sub clock (up to 50 kHz : 100 kHz oscillation clock divided by two) is allowed.
- 16-bit input capture (8 channels)
  Detects rising, falling, or both edges.
  16-bit capture register × 8
  The value of a 16-bit free-run timer counter is latched upon detection of an edge input to pin and an interrupt request is generated.

(Continued)

For the information for microcontroller supports, see the following web site.
This web site includes the **"Customer Design Review Supplement"** which provides the latest cautions on system development and the minimal requirements to be checked to prevent problems before the system development.

http://edevice.fujitsu.com/micom/en-support/

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(Continued)

- 16-bit reload timer (4 channels)
  16-bit reload timer operation (select toggle output or one-shot output)
  Selectable event count function
- Real time watch timer (main clock)
  Operates directly from oscillator clock.
  Interrupt can be generated by second/minute/hour/date counter overflow.
- PPG timer (6 channels)
  Output pins (3 channels), external trigger input pin (1 channel)
  Operation clock frequencies : f_{CP}, $f_{CP}/2^2$, $f_{CP}/2^4$, $f_{CP}/2^6$
- Delay interrupt
  Generates interrupt for task switching.
  Interrupts to CPU can be generated/cleared by software setting.
- External interrupts (8 channels)
  8-channel independent operation
  Interrupt source setting available : “L” to “H” edge/ “H” to “L” edge/ “L” level/ “H” level.
- 8/10-bit A/D converter (8 channels)
  Conversion time : 3 µs (at f_{CP} = 32 MHz)
  External trigger activation available (P50/INT0/ADTG)
  Internal timer activation available (16-bit reload timer 1)
- UART(LIN/SCI) (4 channels)
  Equipped with full duplex double buffer
  Clock-asynchronous or clock-synchronous serial transfer is available
- CAN interface (4 channels : CAN0 and CAN2, and CAN1 and CAN3 share transmission and reception pins, and interrupt control registers).
  Conforms to CAN specifications version 2.0 Part A and B.
  Automatic resend in case of error.
  Automatic transfer in response to remote frame.
  16 prioritized message buffers for data and ID
  Multiple message support
  Flexible configuration for receive filter : Full bit compare/full bit mask/two partial bit masks
  Supports up to 1 Mbps
  CAN wakeup function (RX connected to INT0 internally)
- LCD controller/driver (32 segment x 4 common)
  Segment driver and command driver with direct LCD panel (display) drive capability
- Reset on detection of low voltage/program loop
  Automatic reset when low voltage is detected
  Program looping detection function
- Stepping motor controller (4 channels)
  High current output for each channel × 4
  Synchronized 8/10-bit PWM for each channel × 2
- Sound generator (2 channels)
  8-bit PWM signal mixed with tone frequency from 8-bit reload counter.
  PWM frequencies : 125 kHz, 62.5 kHz, 31.2 kHz, 15.6 kHz (at f_{CP} = 32 MHz)
  Tone frequencies : PWM frequency /2/ , divided by (reload frequency +1)
- Input/output ports
  General-purpose input/output port (CMOS output) 93 ports
- Function for port input level selection
  Automotive/CMOS-Schmitt
- Flash memory security function
  Protects the contents of Flash memory (Flash memory product only)

Pin no.	Pin name	I/O circuit type*1	Function
104	P13	I	General-purpose I/O port
	PPG5		16-bit PPG ch.5 output pin
109	P14	I	General-purpose I/O port
	TIN2		16-bit reload timer ch.2 TIN input pin
	IN1		Input capture ch.1 trigger input pin
110	P15	I	General-purpose I/O port
	IN0		Input capture ch.0 trigger input pin
111	COM0	P	LCD controller/driver common output pin
112	COM1	P	LCD controller/driver common output pin
113	COM2	P	LCD controller/driver common output pin
114	COM3	P	LCD controller/driver common output pin
115	P22	F	General-purpose I/O port
	SEG00		LCD controller/driver segment output pin
116	P23	F	General-purpose I/O port
	SEG01		LCD controller/driver segment output pin
117	P24	F	General-purpose I/O port
	SEG02		LCD controller/driver segment output pin
118	P25	F	General-purpose I/O port
	SEG03		LCD controller/driver segment output pin
119	P26	F	General-purpose I/O port
	SEG04		LCD controller/driver segment output pin
120	P27	F	General-purpose I/O port
	SEG05		LCD controller/driver segment output pin
1	P30	F	General-purpose I/O port
	SEG06		LCD controller/driver segment output pin
2	P31	F	General-purpose I/O port
	SEG07		LCD controller/driver segment output pin
3	P32	F	General-purpose I/O port
	SEG08		LCD controller/driver segment output pin
4	P33	F	General-purpose I/O port
	SEG09		LCD controller/driver segment output pin
5	P34	F	General-purpose I/O port
	SEG10		LCD controller/driver segment output pin
6	P35	F	General-purpose I/O port
	SEG11		LCD controller/driver segment output pin

(Continued)

Pin no.	Pin name	I/O circuit type*1	Function
7	P36	F	General-purpose I/O port
	SEG12		LCD controller/driver segment output pin
8	P37	F	General-purpose I/O port
	SEG13		LCD controller/driver segment output pin
9	P40	F	General-purpose I/O port
	SEG14		LCD controller/driver segment output pin
10	P41	F	General-purpose I/O port
	SEG15		LCD controller/driver segment output pin
11	P42	F	General-purpose I/O port
	SEG16		LCD controller/driver segment output pin
12	P43	F	General-purpose I/O port
	SEG17		LCD controller/driver segment output pin
18	P44	F	General-purpose I/O port
	SEG18		LCD controller/driver segment output pin
19	P45	F	General-purpose I/O port
	SEG19		LCD controller/driver segment output pin
20	P46	F	General-purpose I/O port
	SEG20		LCD controller/driver segment output pin
21	P47	F	General-purpose I/O port
	SEG21		LCD controller/driver segment output pin
37	P50	I	General-purpose I/O port
	INT0		INT0 external interrupt input pin
	ADTG		A/D converter external trigger input pin
58	P51	I	General-purpose I/O port
	INT1		INT1 external interrupt input pin
	RX1		CAN interface 1 RX input pin
	RX3		CAN interface 3 RX input pin
59	P52	I	General-purpose I/O port
	TX1		CAN interface 1 TX output pin
	TX3		CAN interface 3 TX output pin
60	P53	I	General-purpose I/O port
	INT3		INT3 external interrupt input pin

(Continued)

Pin no.	Pin name	I/O circuit type*1	Function
61	P54	I	General-purpose I/O port
	TX0		CAN interface 0 TX output pin
	TX2		CAN interface 2 TX output pin
	SGA1		Sound generator ch.1 SGA output pin
63	P55	I	General-purpose I/O port
	RX0		CAN interface 0 RX input pin
	RX2		CAN interface 2 RX input pin
	INT2		INT2 external interrupt input pin
91	P56	I	General-purpose I/O port
	SGO0		Sound generator ch.0 SGO output pin
	FRCK		Free-run timer clock input pin
92	P57	I	General-purpose I/O port
	SGA0		Sound generator ch.0 SGA output pin
39	P60	H	General-purpose I/O port
	AN0		A/D converter input pin
40	P61	H	General-purpose I/O port
	AN1		A/D converter input pin
41	P62	H	General-purpose I/O port
	AN2		A/D converter input pin
42	P63	H	General-purpose I/O port
	AN3		A/D converter input pin
43	P64	H	General-purpose I/O port
	AN4		A/D converter input pin
44	P65	H	General-purpose I/O port
	AN5		A/D converter input pin
45	P66	H	General-purpose I/O port
	AN6		A/D converter input pin
46	P67	H	General-purpose I/O port
	AN7		A/D converter input pin
67	P70	L	General-purpose output-only port
	PWM1P0		Stepping motor controller ch.0 output pin
68	P71	L	General-purpose output-only port
	PWM1M0		Stepping motor controller ch.0 output pin
69	P72	L	General-purpose output-only port
	PWM2P0		Stepping motor controller ch.0 output pin

(Continued)

(Continued)

Pin no.	Pin name	I/O circuit type*1	Function
26	PD2	I	General-purpose I/O port
	SCK2		UART ch.2 serial clock I/O pin
27	PD3	J	General-purpose I/O port
	SIN3		UART ch.3 serial data input pin
28	PD4	I	General-purpose I/O port
	SOT3		UART ch.3 serial data output pin
29	PD5	I	General-purpose I/O port
	SCK3		UART ch.3 serial clock I/O pin
30	PD6	I	General-purpose I/O port
	TOT2		16-bit reload timer ch.2 TOT output pin
56	PE0	I	General-purpose I/O port
	TOT3		16-bit reload timer ch.3 TOT output pin
57	PE1	I	General-purpose I/O port
	TIN3		16-bit reload timer ch.3 TIN input pin
64	PE2	I	General-purpose I/O port
	SGO1		Sound generator ch.1 SGO output pin
62	RSTO	N	Internal reset signal output pin
65, 75, 85	DVCC	—	Power supply input pins dedicated for high current output buffer
66, 76, 86	DVSS	—	Power supply GND pins dedicated for high current output buffer
35	AVCC	—	A/D converter dedicated power supply input pin
38	AVSS	—	A/D converter dedicated power supply GND pin
36	AVRH	—	A/D converter Vref+ input pin. Vref- is fixed to AVSS.
89	MD0	D	Mode setting input pin. Connect to VCC pin.
88	MD1	D	Mode setting input pin. Connect to VCC pin.
87	MD2	D/E*2	Mode setting input pin. Connect to VSS pin.
17	C	—	External capacitor pin. Connect a 0.1 μF capacitor between this pin and the VSS pin.
15, 105	VCC	—	Power supply input pins
16, 47, 106	VSS	—	GND power supply pins

*1 : For I/O circuit type, refer to “ ■ I/O CIRCUIT TYPES”.

*2 : The I/O circuit type is D for Flash memory products and E for evaluation products.

- **Notes on operating in PLL clock mode**

On this microcontroller, if in case the crystal oscillator breaks off or an external reference clock input stops while the PLL clock mode is selected, a self-oscillator circuit contained in the PLL may continue its operation at its self-running frequency. However, FUJITSU SEMICONDUCTOR will not guarantee results of operations if such failure occurs.

- **Crystal oscillator circuit**

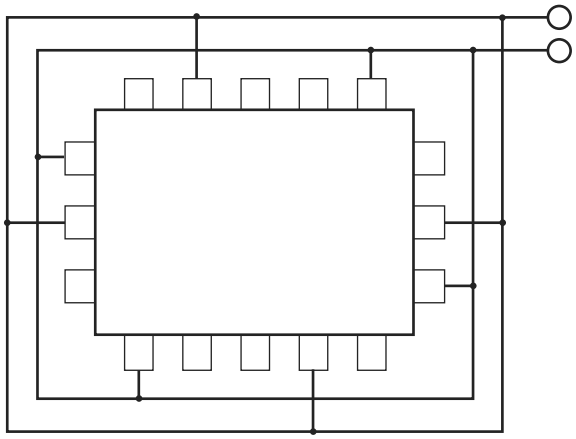
Noise around the X0/X1, or X0A/X1A pins may cause this device to operate abnormally. In the interest of stable operation it is strongly recommended that printed circuit artwork places ground bypass capacitors as close as possible to the X0/X1, X0A/X1A and crystal oscillator (or ceramic oscillator) and that oscillator lines do not cross the lines of other circuits.

Please ask each crystal maker to evaluate the oscillational characteristics of the crystal and this device.

- **Power supply pins**

Devices including multiple VCC or VSS pins are designed such that pins that need to be at the same potential are interconnected internally to prevent malfunctions such as latch-up. To reduce unnecessary radiation, prevent malfunctioning of the strobe signal due to the rise of ground level, and observe the standard for total output current, be sure to connect the VCC and VSS pins to the power supply and ground externally.

Always connect all of the VCC pins to the same potential and all of the VSS pins to ground as shown in the following diagram. The device will not operate correctly if multiple VCC or VSS pins are connected to different voltages, even if those voltages are within the guaranteed operating ranges.



Power supply input pins (Vcc/Vss)

In addition, care must be given to connecting the VCC and VSS pins of this device to the current supply source with as low impedance as possible. It is recommended that a 1.0 μF bypass capacitor be connected between the VCC and VSS pins as close to the pins as possible.

- **Sequence for connecting the A/D converter power supply and analog inputs**

The A/D converter power supply (AV_{CC}, AVRH) and analog inputs (AN0 to AN7) must be applied after the digital power supply (V_{CC}) is switched on. When turning the power off, the A/D converter power supply and analog inputs must be disconnected before the digital power supply is switched off (V_{CC}). Ensure that AVRH does not exceed AVcc during either power-on or power-off. Even when pins which double as analog input pins are used as input ports, be sure that the input voltage does not exceed AV_{CC} (turning on/off the analog and digital power supplies simultaneously is acceptable).

- **Serial communication**

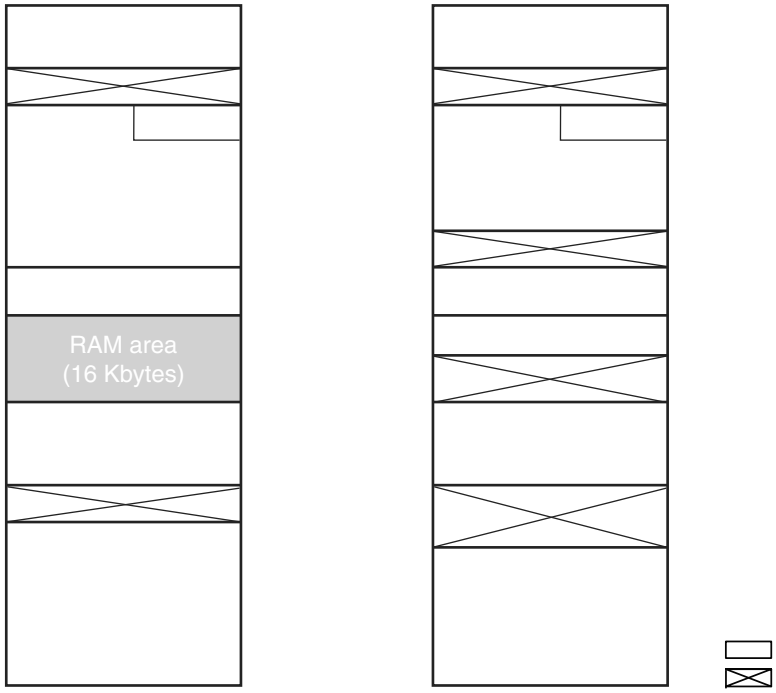
In serial communication, reception of wrong data may occur due to noise or other causes. Therefore, design a printed circuit board to prevent noise from occurring. Taking account of the reception of wrong data, detect errors by measures such as adding a checksum to the end of data. If an error is detected, retransmit the data.

- **Characteristic difference between flash device and MASK ROM device**

In the flash device and the MASK ROM device, the electrical characteristic including current consumption, ESD, latch-up, the noise characteristic, and oscillation characteristic, etc. is different according to the difference between the chip layout and the memory structure.

Reconfirm the electrical characteristic when the product is replaced by another product of the same series.

■ MEMORY MAP



MB90F922 / MB90922
MB90F923 / MB90F924

Parts No.	ROM (Flash) capacitance	RAM capacitance	Address #1	Address #2	Address #3
MB90F922NC/F922NCS/922NCS	256 Kbytes	10 Kbytes	FC0000H	004000H	002900H
MB90F923NC/F923NCS	384 Kbytes	16 Kbytes	FA0000H	004A00H	003700H
MB90F924NC/F924NCS	512 Kbytes	24 Kbytes	F80000H	006A00H	003700H

* : Evaluation products do not contain internal ROM. Treat this address as the ROM decode area used by the tools.

Note: To select models without the ROM mirror function, refer to the “ROM Mirror Function Selection Module” in Hardware Manual. The image of the ROM data in the FF bank appears at the top of the 00 bank, in order to enable efficient use of small C compiler models. The lower 16-bits of the FF bank addresses are allocated to the same addresses as the lower 16-bits of the 00 bank, making it possible to reference tables in ROM without declaring the “far” modifier with the pointers. For example, when an access is made to the address 00C000H, the actual address to be accessed is FFC000H in ROM. Because the size of the FF bank ROM area exceeds 32 Kbytes, it is not possible to view the entire region in the 00 bank image. Therefore because the ROM data from FF8000H to FFFFFFH appears in the image from 008000H to 00FFFFH, it is recommended that ROM data tables be stored in the area from FF8000H to FFFFFFH.

List of Message Buffers (ID Registers)

Address				Register	Abbre-viation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003A00H to 003A1FH	003B00H to 003B1FH	003700H to 00371FH	003800H to 00381FH	General-purpose RAM	—	R/W	XXXXXXXXB to XXXXXXXXB
003A20H	003B20H	003720H	003820H	ID register 0	IDR0	R/W	XXXXXXXXB XXXXXXXXB
003A21H	003B21H	003721H	003821H				
003A22H	003B22H	003722H	003822H				XXXXX---B XXXXXXXXB
003A23H	003B23H	003723H	003823H				
003A24H	003B24H	003724H	003824H	ID register 1	IDR1	R/W	XXXXXXXXB XXXXXXXXB
003A25H	003B25H	003725H	003825H				
003A26H	003B26H	003726H	003826H				XXXXX---B XXXXXXXXB
003A27H	003B27H	003727H	003827H				
003A28H	003B28H	003728H	003828H	ID register 2	IDR2	R/W	XXXXXXXXB XXXXXXXXB
003A29H	003B29H	003729H	003829H				
003A2AH	003B2AH	00372AH	00382AH				XXXXX---B XXXXXXXXB
003A2BH	003B2BH	00372BH	00382BH				
003A2CH	003B2CH	00372CH	00382CH	ID register 3	IDR3	R/W	XXXXXXXXB XXXXXXXXB
003A2DH	003B2DH	00372DH	00382DH				
003A2EH	003B2EH	00372EH	00382EH				XXXXX---B XXXXXXXXB
003A2FH	003B2FH	00372FH	00382FH				
003A30H	003B30H	003730H	003830H	ID register 4	IDR4	R/W	XXXXXXXXB XXXXXXXXB
003A31H	003B31H	003731H	003831H				
003A32H	003B32H	003732H	003832H				XXXXX---B XXXXXXXXB
003A33H	003B33H	003733H	003833H				
003A34H	003B34H	003734H	003834H	ID register 5	IDR5	R/W	XXXXXXXXB XXXXXXXXB
003A35H	003B35H	003735H	003835H				
003A36H	003B36H	003736H	003836H				XXXXX---B XXXXXXXXB
003A37H	003B37H	003737H	003837H				
003A38H	003B38H	003738H	003838H	ID register 6	IDR6	R/W	XXXXXXXXB XXXXXXXXB
003A39H	003B39H	003739H	003839H				
003A3AH	003B3AH	00373AH	00383AH				XXXXX---B XXXXXXXXB
003A3BH	003B3BH	00373BH	00383BH				
003A3CH	003B3CH	00373CH	00383CH	ID register 7	IDR7	R/W	XXXXXXXXB XXXXXXXXB
003A3DH	003B3DH	00373DH	00383DH				
003A3EH	003B3EH	00373EH	00383EH				XXXXX---B XXXXXXXXB
003A3FH	003B3FH	00373FH	00383FH				

(Continued)

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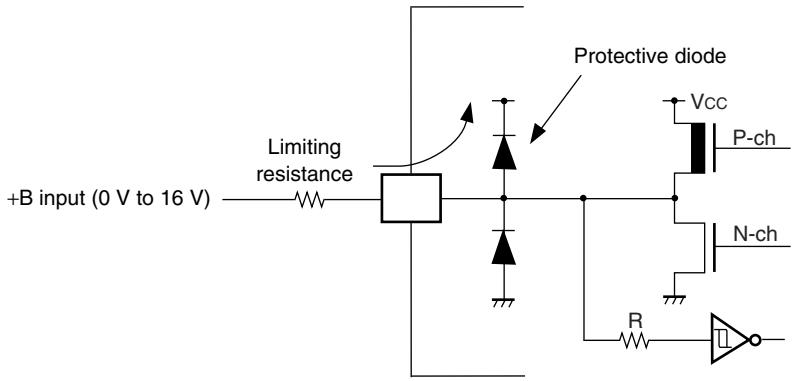
*5 : Average output current is defined as the average value of the current flowing through any one of the corresponding pins within a period of 100 ms. The “average value” can be calculated by multiplying the “operating current” by the “operating factor”.

*6 : Average total output current is defined as the average value of the current flowing through all of the corresponding pins within a period of 100 ms. The “average value” can be calculated by multiplying the “operating current” by the “ operating factor”.

*7 :
- Applicable to pins: P10 to P15,P50 to P57,P60 to P67,P70 to P77,P80 to P87,PC0 to PC7,PD0 to PD6, PE0 to PE2
- Use within recommended operating conditions.
- Use at DC voltage (current) .
- The +B signal should always be applied with a limiting resistance placed between the +B signal and the microcontroller.
- The value of the limiting resistance should be set so that when the +B signal is applied, the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0 V) , the microcontroller may partially malfunction on power supplied through the +B signal pin.
- Note that if the +B input is applied during power-on, the power supply voltage may reach a level such that the power-on reset does not function due to the power supplied from the +B signal.
- Care must be taken not to leave +B input pins open.
- Note that analog system input/output pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signal inputs.
- Sample recommended circuit :

• Input/output equivalent circuit



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

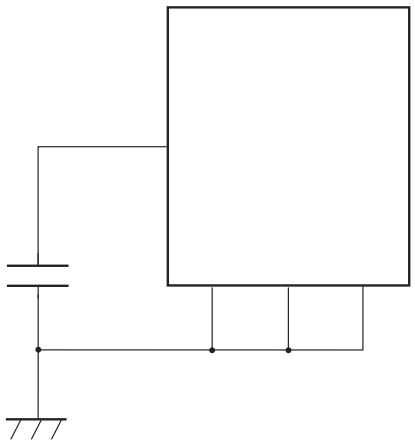
2. Recommended Operating Conditions

(V_{SS} = DV_{SS} = AV_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
Power supply voltage	V_{CC} AV_{CC} DV_{CC}	4.0	5.5	V	The low voltage detection reset operates when the power supply voltage reaches 4.2 V ± 0.2 V.
		4.4	5.5	V	Maintain stop operation status The low voltage detection reset operates when the power supply voltage reaches 4.2 V ± 0.2 V.
Smoothing capacitor*	C_S	0.1	1.0	µF	Use a ceramic capacitor or other capacitor of equivalent frequency characteristics. Use a capacitor with a capacitance greater than this capacitor as the bypass capacitor for the V_{CC} pin.
Operating temperature	T_A	− 40	+ 105	°C	

* : Refer to the following diagram for details on the connection of the smoothing capacitor C_S.

• C pin connection diagram



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

(Continued)

(V_{CC} = 5.0 V ±10%, V_{SS} = DV_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
LCDC leakage current	I_{LCDC}	V0 to V3, COMm (m = 0 to 3) , SEGn, (n = 00 to 31)	—	—	—	5.0	µA	
LCD output impedance	Rvcom	COMn (n = 0 to 3)	—	—	—	4.5	kΩ	
	Rvseg	SEGn (n = 00 to 31)	—	—	—	17	kΩ	

* : Power supply current values assume an external clock supplied to the X1 pin and X1A pin. Users must be aware that power supply current levels differ depending on whether an external clock or oscillator is used.

(4) UART0/1/2/3 (LIN/SCI)

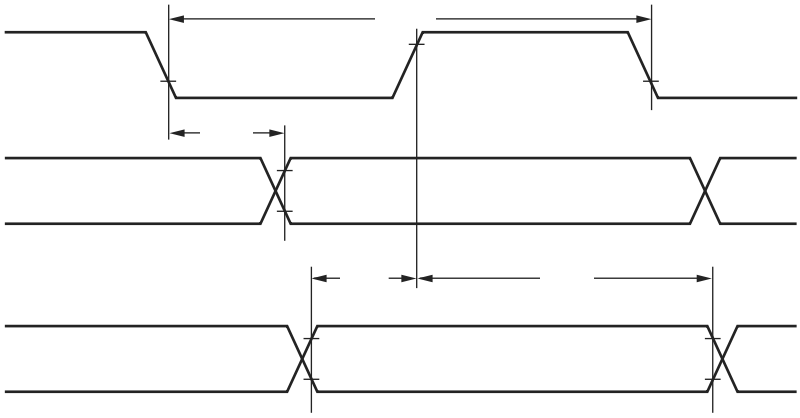
- **Bit setting: ESCR0/1/2/3:SCES=0, ECCR0/1/2/3:SCDE=0**

(V_{CC} = 5.0 V±10 %, V_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

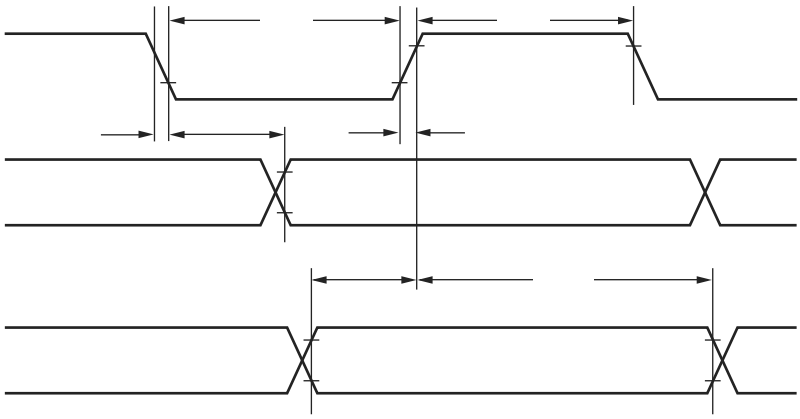
Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		− 50	+ 50	ns
Valid SIN → SCK ↑	t_{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXI}			0	—	ns
Serial clock “L” pulse width	t_{SLSH}	SCK0 to SCK3	External shift clock mode output pin C_L = 80 pF + 1TTL	3 t_{CP} − t_R	—	ns
Serial clock “H” pulse width	t_{SHSL}			t_{CP} + 10	—	ns
SCK ↓ → SOT delay time	t_{SLOVE}	SCK0 to SCK3, SOT0 to SOT3		—	2 t_{CP} + 60	ns
Valid SIN → SCK ↑	t_{IVSHE}	SCK0 to SCK3, SIN0 to SIN3		30	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXE}			t_{CP} + 30	—	ns
SCK ↓ time	t_F	SCK0 to SCK3		—	10	ns
SCK ↑ time	t_R			—	10	ns

Notes : • Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
• C_L is the load capacitance connected to the pin during testing.
• t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

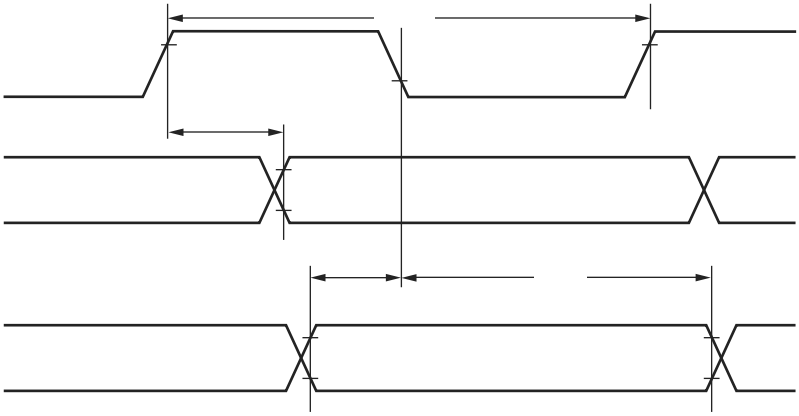
- Internal shift clock mode



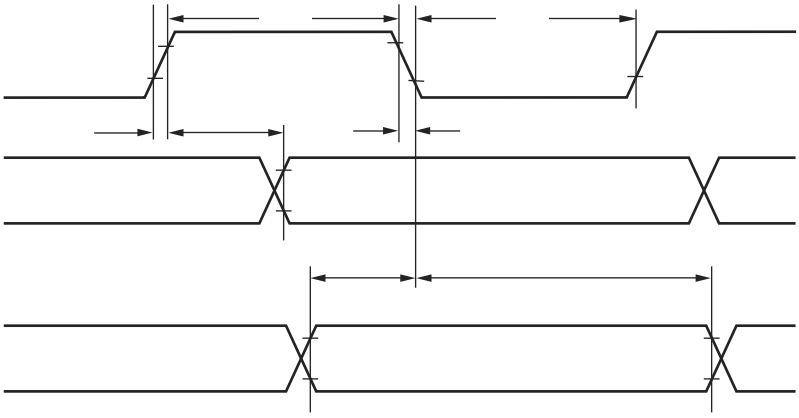
- External shift clock mode



- Internal shift clock mode



- External shift clock mode

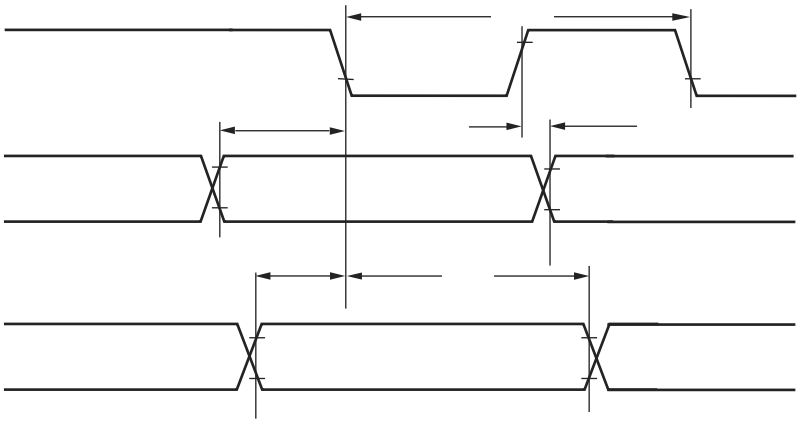


• **Bit setting: ESCR0/1/2/3:SCES=0, ECCR0/1/2/3:SCDE=1**

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCK0 to SCK3, SOT0 to SOT3		– 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSLI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↓ → valid SIN hold time	t_{SLIXI}			0	—	ns
SOT → SCK ↓ delay time	t_{SOVLI}	SCK0 to SCK3, SOT0 to SOT3		3 t_{CP} – 70	—	ns

Notes : • Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
• C_L is the load capacitance connected to the pin during testing.
• t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

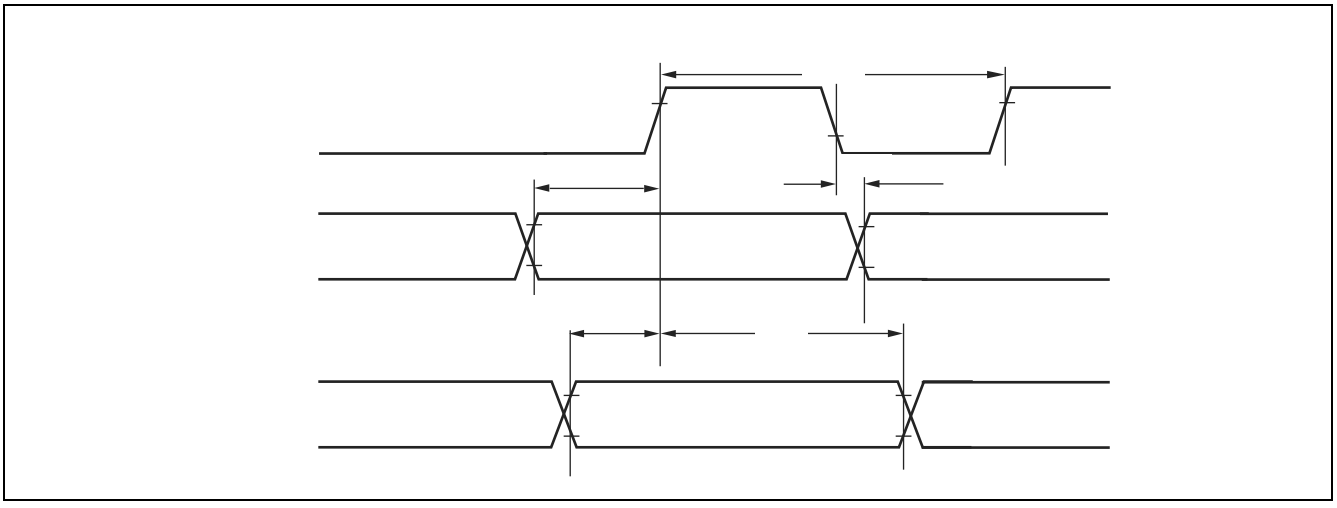


• **Bit setting: ESCR0/1/2/3:SCES=1, ECCR0/1/2/3:SCDE=1**

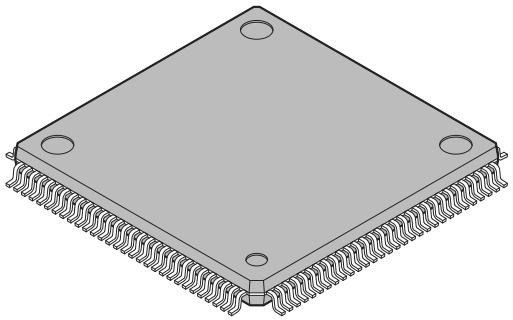
(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		– 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXI}			0	—	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCK0 to SCK3, SOT0 to SOT3		3 t_{CP} – 70	—	ns

Notes :
- Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
- C_L is the load capacitance connected to the pin during testing.
- t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

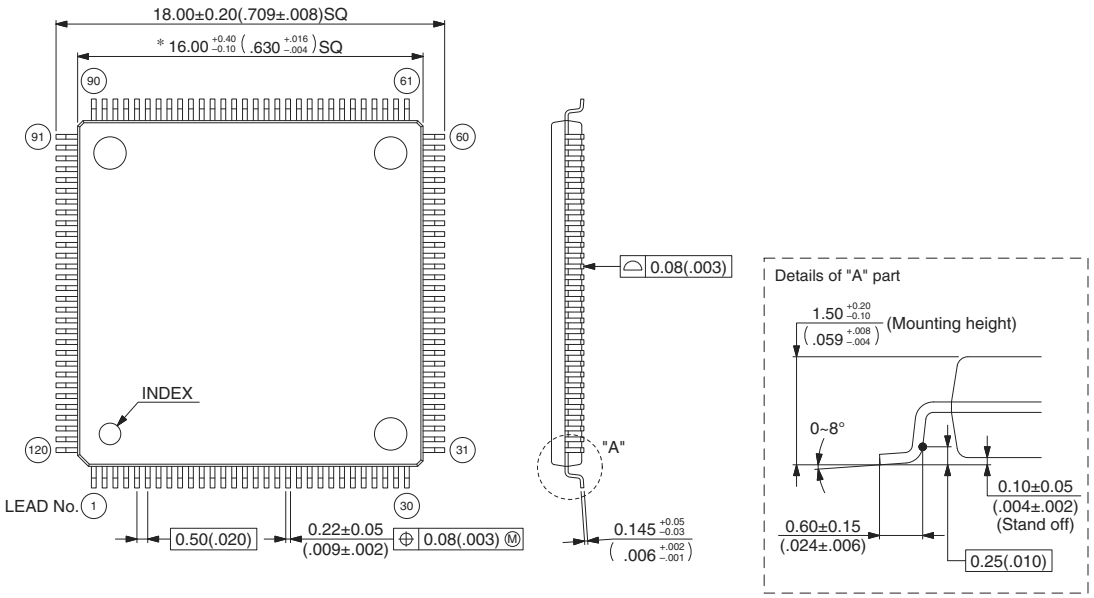


■ PACKAGE DIMENSION

120-pin plastic LQFP		
	Lead pitch	0.50 mm
	Package width × package length	16.0 × 16.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.88 g
(FPT-120P-M21)	Code (Reference)	P-LFQFP120-16×16-0.50

120-pin plastic LQFP
(FPT-120P-M21)

Note 1) * : These dimensions do not include resin protrusion.
Resin protrusion is +0.25(.010) MAX(each side).
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values.

Please check the latest package dimension at the following URL.
http://edevice.fujitsu.com/package/en-search/

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